

Serial No. 10/033,797

IN THE SPECIFICATION:

Page 1, before line 5, cancel the prior insertion and  
replace with:

137 This is a Division of application Serial No. 09/603,203,  
filed June 26, 2000, now ~~allowed~~ U.S. Patent No. 6,348,273.

Page 10, lines 5-10, cancel and replace with:

132 Conditions employed for bonding other than those mentioned  
above, for example, cooling condition and others can be in  
accordance with the disclosure of Japanese Patent Application  
No.10-52971 filed on February 18, 1998, whose U.S. counterpart  
has issued as Patent No. 6,390,354. Therefore, the disclosure  
of Japanese Patent Application No.10-52971 filed on February 18,  
1998 is incorporated herein by reference.